

Product Description

SF-65000U is one of a series of high tensile, high tear fluorosilicone compounds. It is designed to process well in molding applications. It can be blended with other members of the series for intermediate hardnesses.

Product Features

- Excellent fuel and solvent resistance.
- Usable over a broad temperature range.

Typical Applications

- Chemical resistant packings and seals.
- Oil and fuel resistant seals, O rings, diaphragms for automotive.
- Heat and cold resistant packings, gaskets for aeronautical.

Typical Properties

Type of HCR	Fluorosilicone
Cure Agent	DBPH Paste (80%)
Durometer	51
Tensile Strength (psi)	1744
Elongation (%)	567
Specific Gravity	1.44
Tear Die B (ppi)	267
Cure Time (minutes)	10
Cure Temp. (°C)	166
Cure Temp. (°F)	330.8
Post Cure Time (hours)	4
Post Cure Temp. (°C)	200
Post Cure Temp. (°F)	392
Ratio of Catalyst to Material	0.8 : 100

Note: Values are not for specification purposes.

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